

REPETITIVE AVALANCHE AND dv/dt RATED HEXFET® TRANSISTOR

IRHNA7264SE

N-CHANNEL SINGLE EVENT EFFECT (SEE) RAD HARD

250Volt, 0.110Ω, (SEE) RAD HARD HEXFET

International Rectifier's (SEE) RAD HARD technology HEXFETs demonstrate virtual immunity to SEE failure. Additionally, under **identical** pre- and post-radiation test conditions, International Rectifier's RAD HARD HEXFETs retain **identical** electrical specifications up to 1×10^5 Rads (Si) total dose. No compensation in gate drive circuitry is required. These devices are also capable of surviving transient ionization pulses as high as 1×10^{12} Rads (Si)/Sec, and return to normal operation within a few microseconds. Since the SEE process utilizes International Rectifier's patented HEXFET technology, the user can expect the highest quality and reliability in the industry.

RAD HARD HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and temperature stability of the electrical parameters.

They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers and high-energy pulse circuits in space and weapons environments.

Product Summary

Absolute Maximum Ratings

		Pre-Radiation	
	Parameter	IRHNA7264SE	Units
I_D @ $V_{GS} = 12V, T_C = 25^\circ C$	Continuous Drain Current	34	A
I_D @ $V_{GS} = 12V, T_C = 100^\circ C$	Continuous Drain Current	21	
I_{DM}	Pulsed Drain Current ①	136	
P_D @ $T_C = 25^\circ C$	Max. Power Dissipation	300	W
	Linear Derating Factor	2.4	W/K⑤
V_{GS}	Gate-to-Source Voltage	± 20	V
EAS	Single Pulse Avalanche Energy ②	500	mJ
I_{AR}	Avalanche Current ①	34	A
EAR	Repetitive Avalanche Energy ①	30	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.0	V/ns
T_J	Operating Junction	-55 to 150	°C
T_{STG}	Storage Temperature Range		
	Package Mounting Surface Temperature	300 (for 5 sec.)	
	Weight	3.3 (typical)	g

Part Number	BV_{DSS}	$R_{DS(on)}$	I_D
IRHNA7264SE	250V	0.110Ω	34A

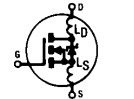
Features:

- Radiation Hardened up to 1×10^5 Rads (Si)
- Single Event Burnout (SEB) Hardened
- Single Event Gate Rupture (SEGR) Hardened
- Gamma Dot (Flash X-Ray) Hardened
- Neutron Tolerant
- Identical Pre- and Post-Electrical Test Conditions
- Repetitive Avalanche Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Surface Mount
- Lightweight

Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

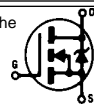
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	250	—	—	V	V _{GS} = 0V, I _D = 1.0 mA
ΔBV _{DSS} /ΔT _J	Temperature Coefficient of Breakdown Voltage	—	—	—	V/°C	Reference to 25°C, I _D = 1.0 mA
RDS(on)	Static Drain-to-Source	—	—	0.110	Ω	V _{GS} = 12V, I _D = 24A
	On-State Resistance	—	—	0.123		V _{GS} = 12V, I _D = 34A ④
VGS(th)	Gate Threshold Voltage	2.5	—	4.5	V	V _{DS} = V _{GS} , I _D = 1.0 mA
g _{fs}	Forward Transconductance	4	—	—	S (r)	V _{DS} > 15V, I _{DS} = 21A ④
IDSS	Zero Gate Voltage Drain Current	—	—	50	μA	V _{DS} = 0.8 x Max Rating, V _{GS} = 0V
		—	—	250		V _{DS} = 0.8 x Max Rating V _{GS} = 0V, T _J = 125°C
IGSS	Gate-to-Source Leakage Forward	—	—	100	nA	V _{GS} = 20V
IGSS	Gate-to-Source Leakage Reverse	—	—	-100	nA	V _{GS} = -20V
Q _g	Total Gate Charge	—	—	185	nC	V _{GS} = 12V, I _D = 34A
Q _{gs}	Gate-to-Source Charge	—	—	55		V _{DS} = Max. Rating x 0.5
Q _{gd}	Gate-to-Drain ("Miller") Charge	—	—	180		
t _{d(on)}	Turn-On Delay Time	—	—	35	ns	V _{DD} = 125V, I _D = 34A, R _G = 2.35Ω
t _r	Rise Time	—	—	200		
t _{d(off)}	Turn-Off Delay Time	—	—	140		
t _f	Fall Time	—	—	75		
L _D	Internal Drain Inductance	—	2.0	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
L _S	Internal Source Inductance	—	6.5	—		Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
C _{iss}	Input Capacitance	—	7800	—	pF	V _{GS} = 0V, V _{DS} = 25V f = 1.0 MHz
C _{oss}	Output Capacitance	—	1250	—		
C _{rss}	Reverse Transfer Capacitance	—	550	—		

Modified MOSFET symbol showing the internal inductances.



Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	34	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier.
I _{SM}	Pulse Source Current (Body Diode) ①	—	—	136		
V _{SD}	Diode Forward Voltage	—	—	1.4	V	T _J = 25°C, I _S = 34A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	—	875	ns	T _J = 25°C, I _F = 34A, di/dt ≤ 100A/μs
Q _{RR}	Reverse Recovery Charge	—	—	12	μC	V _{DD} ≤ 50V ④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .				



Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{thJC}	Junction-to-Case	—	—	0.42	K/W ⑤	soldered to a copper-clad PC board
R _{thJ-PCB}	Junction-to-PC board	—	TBD	—		

IRHNA7264SE Device

Radiation Characteristics

Radiation Performance of Rad Hard HEXFETs

International Rectifier Radiation Hardened HEXFETs are tested to verify their hardness capability. The hardness assurance program at International Rectifier uses two radiation environments.

Every manufacturing lot is tested in a low dose rate (total dose) environment per MIL-STD-750, test method 1019. International Rectifier has imposed a standard gate voltage of 12 volts per note 6 and a V_{DSS} bias condition equal to 80% of the device rated voltage per note 7. Pre- and post-radiation limits of the devices irradiated to 1×10^5 Rads (Si) are identical and are presented in Table 1. The values in Table 1 will be met for either of the two low dose rate test circuits that are used.

Both pre- and post-radiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison. It should be noted that at a radiation level of 1×10^5 Rads (Si), no change in limits are specified in DC parameters.

High dose rate testing may be done on a special request basis, using a dose rate up to 1×10^{12} Rads (Si)/Sec.

International Rectifier radiation hardened HEXFETs have been characterized in neutron and heavy ion Single Event Effects (SEE) environments. Single Event Effects characterization is shown in Table 3.

Table 1. Low Dose Rate ⑥ ⑦

Parameter		IRHNA7264SE		Units	Test Conditions ⑩
		100K Rads (Si) min.	max.		
BV_{DSS}	Drain-to-Source Breakdown Voltage	250	—	V	$V_{GS} = 0V, I_D = 1.0 \text{ mA}$
$V_{GS(th)}$	Gate Threshold Voltage ④	2.0	4.5	nA	$V_{GS} = V_{DS}, I_D = 1.0 \text{ mA}$
I_{GSS}	Gate-to-Source Leakage Forward	—	100		$V_{GS} = 20V$
I_{GSS}	Gate-to-Source Leakage Reverse	—	-100		$V_{GS} = -20V$
I_{DSS}	Zero Gate Voltage Drain Current	—	50	μA	$V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0V$
$R_{DS(on)1}$	Static Drain-to-Source ④ On-State Resistance One	—	0.110	Ω	$V_{GS} = 12V, I_D = 21A$
V_{SD}	Diode Forward Voltage ④	—	1.4	V	$T_C = 25^\circ C, I_S = 34A, V_{GS} = 0V$

Table 2. High Dose Rate ⑧

Parameter	Description	10^{11} Rads (Si)/sec			10^{12} Rads (Si)/sec			Units	Test Conditions
		Min.	Typ.	Max.	Min.	Typ.	Max.		
V_{DSS}	Drain-to-Source Voltage	—	—	200	—	—	200	V	Applied drain-to-source voltage during gamma-dot
I_{PP}	Peak radiation induced photo-current	—	10	—	—	10	—	A	Peak radiation induced photo-current
di/dt	Rate of rise of photo-current	—	16	—	—	2.3	—	A/ μsec	Rate of rise of photo-current
L_1	Circuit inductance required to limit di/dt	—	1	—	—	20	—	μH	Circuit inductance required to limit di/dt

Table 3. Single Event Effects ⑨

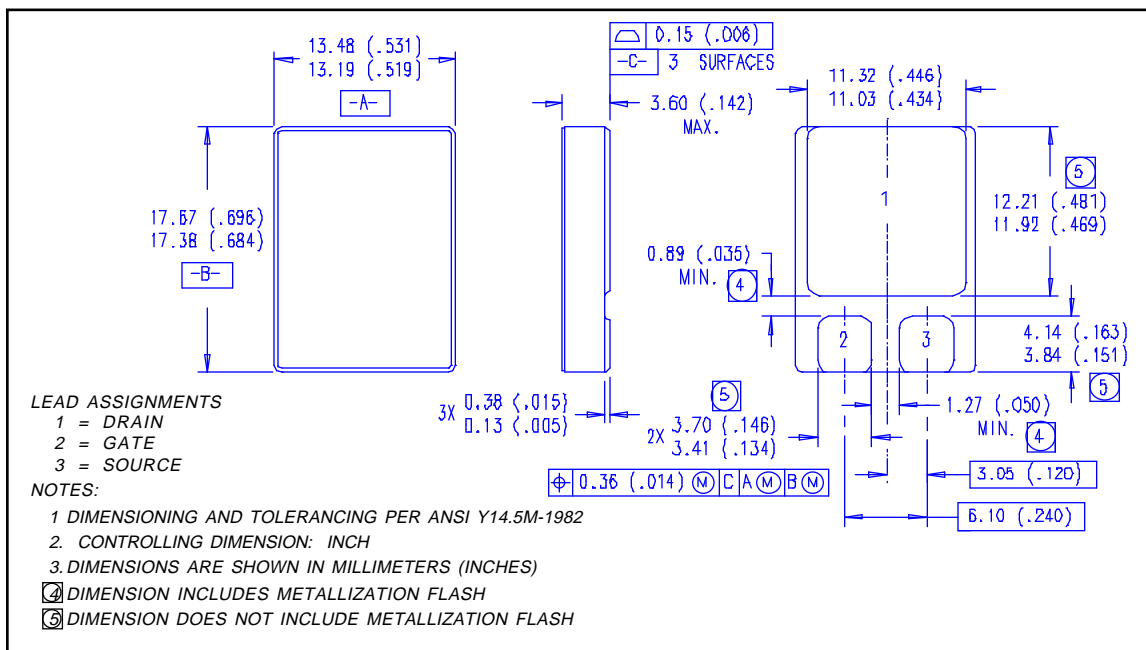
Parameter	Typ.	Units	Ion	LET (Si) (MeV/mg/cm ²)	Fluence (ions/cm ²)	Range (μm)	V_{DS} Bias (V)	V_{GS} Bias (V)
BV_{DSS}	250	V	Ni	28	1×10^5	~35	200	-5

IRHNA7264SE Devices

Radiation Characteristics

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
Refer to current HEXFET reliability report.
- ② @ $V_{DD} = 50V$, Starting $T_J = 25^{\circ}C$,
 $E_{AS} = [0.5 * L * (I_L^2) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]$
Peak $I_L = 34A$, $V_{GS} = 12V$, $25 \leq R_G \leq 200\Omega$
- ③ $I_{SD} \leq 34A$, $di/dt \leq 170 A/\mu s$,
 $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^{\circ}C$
Suggested $R_G = 2.35\Omega$
- ④ Pulse width $\leq 300 \mu s$; Duty Cycle $\leq 2\%$
- ⑤ $K/W = ^{\circ}C/W$
 $W/K = W/^{\circ}C$
- ⑥ **Total Dose Irradiation with VGS Bias.**
12 volt V_{GS} applied and $V_{DS} = 0$ during irradiation per MIL-STD-750, method 1019.
- ⑦ **Total Dose Irradiation with VDS Bias.**
 $V_{DS} = 0.8$ rated BV_{DSS} (pre-radiation) applied and $V_{GS} = 0$ during irradiation per MIL-STD-750, method 1019.
- ⑧ This test is performed using a flash x-ray source operated in the e-beam mode (energy ~ 2.5 MeV), 30 nsec pulse.
- ⑨ Process characterized by independent laboratory.
- ⑩ All Pre-Radiation and Post-Radiation test conditions are **identical** to facilitate direct comparison for circuit applications.

Case Outline and Dimensions — SMD-2



International
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Data and specifications subject to change without notice.

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